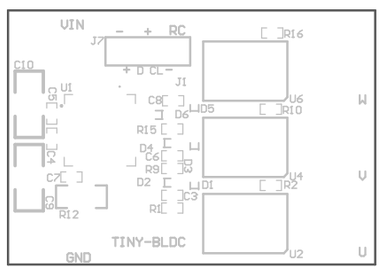
Layer Stack Up Detail for: TINY-BLDC

Layer Name

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Paste				
2	Top Overlay				
3	Top Solder	Solder Resist	0.40mil	3.5	
4	Top Layer	Copper	1.40mil		
5	Dielectric1	FR-4	10.00mil	4.2	
6	Signal Layer 1	Copper	1.42mil		
7	Dielectric 3		5.00mil	4.2	
8	GND Plane	Copper	1.42mil		
9	Dielectric 2		10.00mil	4.2	
10	Bottom Layer	Copper	1.40mil		
11	Bottom Solder	Solder Resist	0.40mil	3.5	
12	Bottom Overlay				
13	Bottom Paste